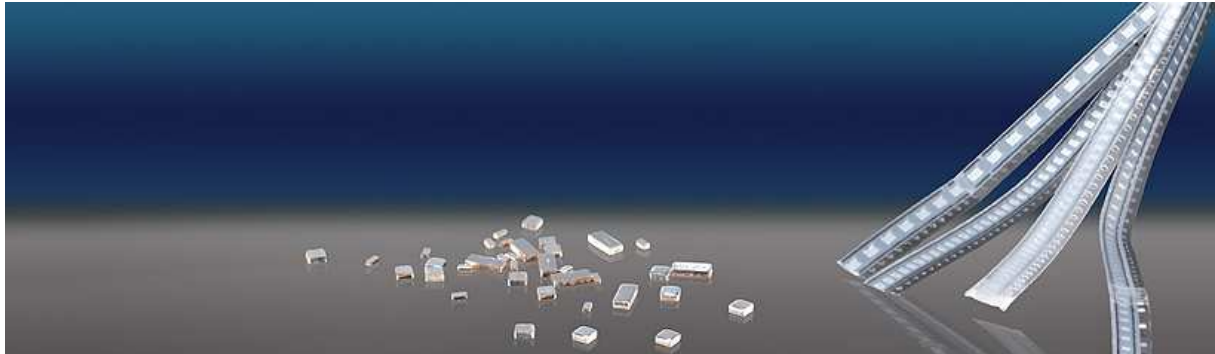


## Heraeus AlSi:Pad



*Traditional single electronic device carriers increasingly are evolving towards becoming multi-functional system boards. Ever more complex functions are compressed on ever less room while simultaneously an enhancement in performance must be obtained. With coated Bonding pads in various designs W. C. Heraeus offers customer oriented solutions that aid the increase in performance while providing consistent quality and stability to the manufacturing steps needed to assemble the device.*

### ■ Applications

- Printed Circuit Board (PCB)
- Ceramic hybrid packages

### ■ Performance characteristics

- High conductivity with proven options of coatings
- Easy and safe handling with automated equipment
- High robustness of quality and consistency
- Extended Shelf Life (ESL) for bondability
- High quality standards and stable production assured through the use of fully automated manufacturing equipment and 100% optical quality check
- Available as RoHS compliant version

## Technical characteristics

- Bondable with Al thick wire and AlSi thin wire
- Bondable with Au gold bonding wire
- Solderable for lead-free and leaded solder materials
- Applicable on all soldered or glued surfaces



## Standard materials

- 0,6 and 0,8 mm thickness
- Carrier material CuSn6

## Functional surfaces

- Bondable surface: AlSi1, Ag
- Soldering side: Sn, SnPb10, CuSn6
- More materials combinations can be provided based on your application



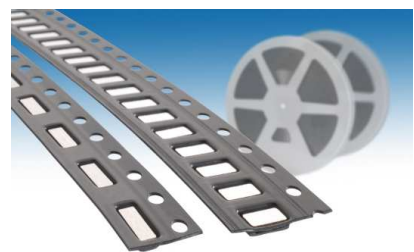
## Standard dimensions (Length x width)

- 0,8 x 1,6 mm
- 1,8 x 1,8 mm
- 1,8 x 4,2 mm
- 2,0 x 2,0 mm
- 2,8 x 2,8 mm



## Packaging

- Tape and reel packing according to DIN EN 60286-3 and EIA standard
- Different orientations possible



**Special solutions by request. Take advantage of our Application Support!**

We have been pioneers in interconnect technology for more than 40 years.

For further information please contact:

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